

Title (en)  
MOULDING METHOD FOR PRODUCING AN ELECTRONIC HOUSING

Title (de)  
FORMVERFAHREN ZUR HERSTELLUNG ELEKTRONIKGEHÄUSE

Title (fr)  
PROCEDE DE MOULAGE POUR FABRIQUER UN BOITIER ELECTRONIQUE

Publication  
**EP 2898528 A1 20150729 (FR)**

Application  
**EP 13762853 A 20130917**

Priority  
• EP 12306128 A 20120918  
• EP 2013069297 W 20130917  
• EP 13762853 A 20130917

Abstract (en)  
[origin: EP2709143A1] The method involves supplying a set of conductive metallizations including beaches and/or circuit conducting tracks on a side of a support (5). A chip (2) is connected to each of the set of metallizations. The chip is molded on the support with an insulating molding material (7) to build a case. The case is separated from the support. A side of the support is arranged in contact with the metallizations comprising adhesive that is liable to deteriorate, where molding of the chip is carried out according to final dimension of an electronic package (1) such as smart card module. An independent claim is also included for a molding equipment.

IPC 8 full level  
**H01L 21/56** (2006.01); **H01L 23/31** (2006.01)

CPC (source: EP US)  
**H01L 21/4803** (2013.01 - US); **H01L 21/565** (2013.01 - EP US); **H01L 21/568** (2013.01 - EP US); **H01L 23/3107** (2013.01 - EP US); **H01L 24/97** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2924/12042** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

Citation (search report)  
See references of WO 2014044684A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 2709143 A1 20140319**; EP 2898528 A1 20150729; US 2015228505 A1 20150813; WO 2014044684 A1 20140327

DOCDB simple family (application)  
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